WHAT IS CLAIMED IS

1. A semiconductor testing device for testing a semiconductor device which has at least one spherical connection terminal, said testing device comprising:

an insulating substrate having an opening formed therein at a position corresponding to a position of said spherical connection terminal; and

a contact member, formed on said insulating substrate, comprising a connection portion connected with said spherical connection terminal, at least said connection portion being deformable and extending into said opening.

2. The semiconductor testing device according to claim 1, wherein said connection portion has a cantilever shape and extends from only one side of said opening.

3. The semiconductor testing device according to claim 1, wherein said connection portion is supported on opposite sides of said opening.

4. The semiconductor testing device

according to claim 2, wherein said connection portion is a wire.

5. The semiconductor testing device according to claim 3, wherein said connection portion is a wire.

6. The semiconductor testing device according to claim 1, wherein said connection portion has at least one opening formed therein.

7. The semiconductor testing device according to claim 6, wherein said opening comprises a slit.

8. The semiconductor testing device according to claim 6, wherein said opening has a circular shape.

9. Th semiconductor testing device according to claim 1, wh rein at least an area, of said connection portion, connected with said spherical

connection terminal, includ s a roughened surface.

10. The semiconductor testing device according to claim 1, further comprising a reinforcement member comprising an elastically deformable material provided as a support for said connection portion.

11. The semiconductor testing device according to claim 10, wherein said reinforcement member comprises an anisotropic conductive rubber.

12. The semiconductor testing device according to claim 10, wherein said reinforcement member comprises a net-shaped elastic member.

13. The semiconductor testing device according to claim 10, wherein said reinforcement member comprises a balloon-shaped member containing one of a gas and a liquid.

14. The semiconductor testing device

according to claim 13, wherein an internal pressure of said balloon-shaped member is changed after said semiconductor device is loaded on said semiconductor testing device.

15. A semiconductor testing device, which is used for performing a test on a semiconductor device having spherical connection terminals, comprising:

a contactor, provided with a single layer of insulating substrate, in which substrate an opening is formed at a position corresponding to a respective one of said spherical connection terminals, said contactor also being provided with a contact portion, which includes a connection portion with which said respective one of said spherical connection terminals is electrically connected, said contact portion being provided on said single layer of insulating substrate so that said connection portion is located on said opening; and

a wiring substrate, on which said contactor is mounted in a manner which permits installation and removal of said contactor onto and from said wiring substrate, said wiring substrate being provided with a first connection terminal which is provided on a first surface, on which said contactor is mounted, and is electrically connected with said contact portion, a second connection terminal which is provided on a second surface, which is opposite to said first surface, and is connected externally, and an interposer which electrically connects said first connection terminal with said second connection terminal.

16. The semiconductor testing devic as claimed in claim 15, wherein said contact portion has a thickness and a hardness such that said contact portion can break an oxide film formed on said respective one of said spherical connection terminals.

17. The semiconductor testing device as claimed in claim 15, wherein an extending portion is formed in said insulating substrate, said extending portion extending in said opening so as to face said contact portion, and partially supporting said contact portion.

18. The semiconductor testing device as claimed in claim 15, wherein a projection, which comes into contact with said contact portion, is formed in said opening, a certain portion of said contact portion being moved when said respective one of said spherical connection terminals is connected with said contact portion, which certain portion is a portion extending from a position to the extending end of said contact portion, at which position said contact portion is supported by said projection.

19. The semiconductor testing device as claimed in claim 18, wherein said projection is made of an lastic material.

20. Th semiconductor testing devic as claimed in claim 18, wh rein said projection is made of a conductive material.

21. The semiconductor testing device as claimed in claim 18, wherein said projection has a spherical shape.

22. The semiconductor testing device as claimed in claim 18, wherein said projection has a ring shape.

23. The semiconductor testing device as claimed in claim 15, wherein a pointed-end portion is formed at an extending-end portion of said contact portion.

24. The semiconductor testing device as claimed in claim 15, wherein a roughened surface is formed on at least one of a surface of said contact portion, with which surface said respective one of said spherical connection terminals comes into contact, and an area of said contact portion, which area comes into contact with said first connection terminal.

25. The semiconductor testing device as claimed in claim 15, wh rein a roughened surface is formed on at least a portion of said first connection terminal, with which portion said contact portion comes into contact.

26. The semiconductor testing device as claimed in claim 15, wherein a positioning arrangement is provided for positioning said contactor with respect to said wiring substrate when said contactor is loaded on said wiring substrate.

27. The semiconductor testing device as claimed in claim 15, wherein said contactor is provided with a non-connection portion at which it is not necessary to electrically connect one of said spherical connection terminals with said contactor, at which non-connection portion an opening is provided but a contact portion is not provided.

28. The semiconductor testing device as claimed in claim 15, wherein the direction in which said contact portion extends is set based on the directions of relative displacement occurring between said respective one of said spherical connection terminals and said contact portion due to a difference in thermal expansion between said contactor and said semiconductor device.

29. The semiconductor t sting device as claimed in claim 15, wh rein an opening is formed in said contact portion at a position at which said respective one of said spherical connection terminals comes into contact with said contact portion.

30. The semiconductor testing device as claimed in claim 15, wherein said wiring substrate comprises a multi-layer substrate.

31. The semiconductor testing device as claimed in claim 15, wherein said insulating substrate comprises a flexible film made of resin and having the property of insulation, and said contact portion comprises a conductive metal layer having flexibility.

32. A semiconductor testing method for a semiconductor device having spherical connection terminals, comprising the steps of:

a) mounting a contactor on a wiring substrate,

wherein:

said contactor is provided with a single layer of insulating substrate, in which substrate an opening is formed at a position corresponding to a respective one of said spherical connection terminals, said contactor also being provided with a contact portion, which includes a connection portion with which

said respective one of said spherical connection terminals is electrically connected, said contact portion being provided on said single layer of insulating substrate so that said connection portion is located on said opening; and

said contactor is mounted on said wiring substrate in a manner which permits installation and removal of said contactor onto and from said wiring substrate, said wiring substrate being provided with a first connection terminal which is provided on a first surface, on which said contactor is mounted, and is electrically connected with said contact portion, a second connection terminal which is provided on a second surface, which is opposite to said first surface, and is connected externally, and an interposer which electrically connects said first connection terminal with said second connection terminal;

b) loading said semiconductor device on said contactor, mounted on said wiring substrate, so that said respective one of said spherical connection terminals is connected with said connection portion of said contact portion; and

c) testing said semiconductor device via said second connection terminal, interposer and first connection terminal of said wiring substrate, said contact portion of said contactor and said respective one of said spherical connection terminals.